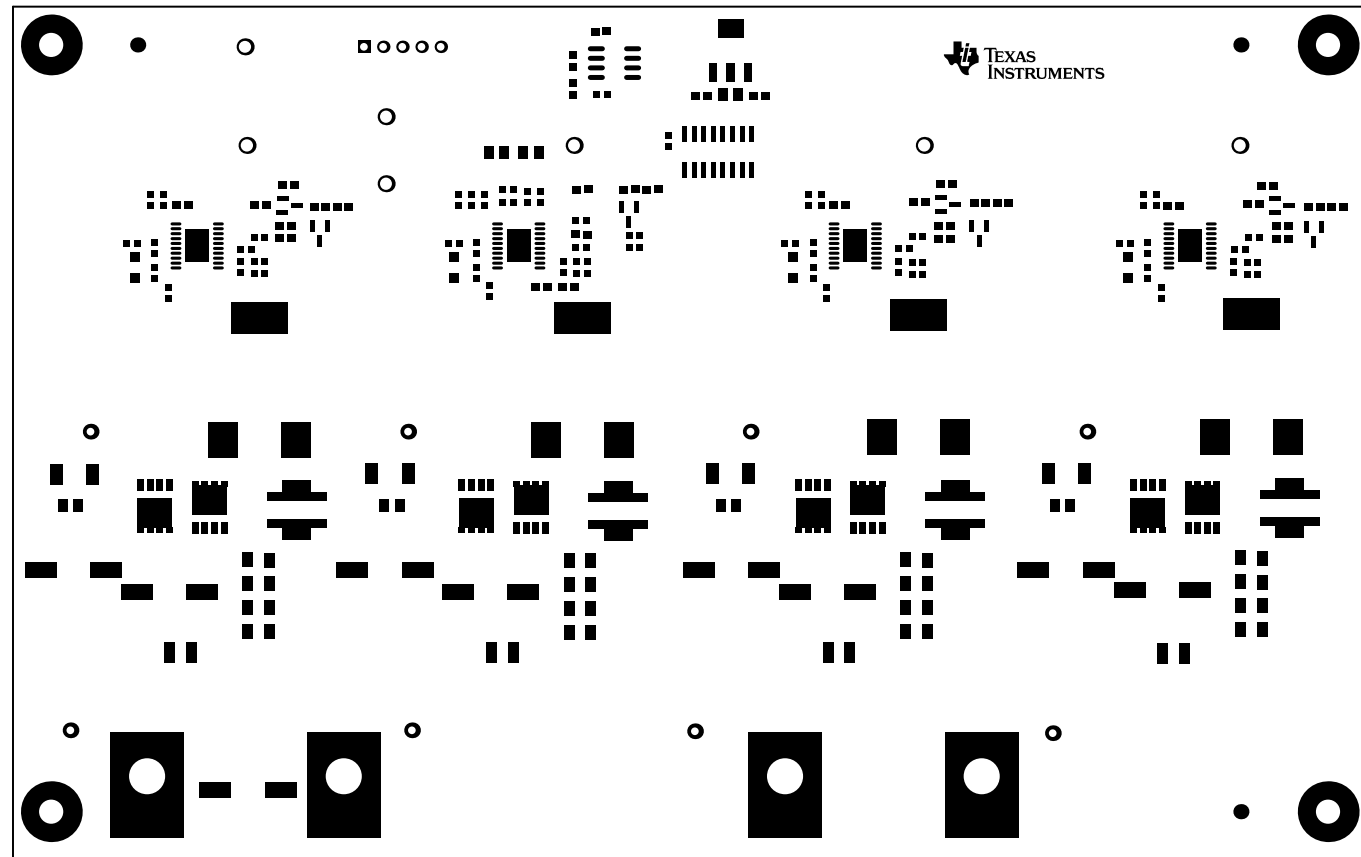
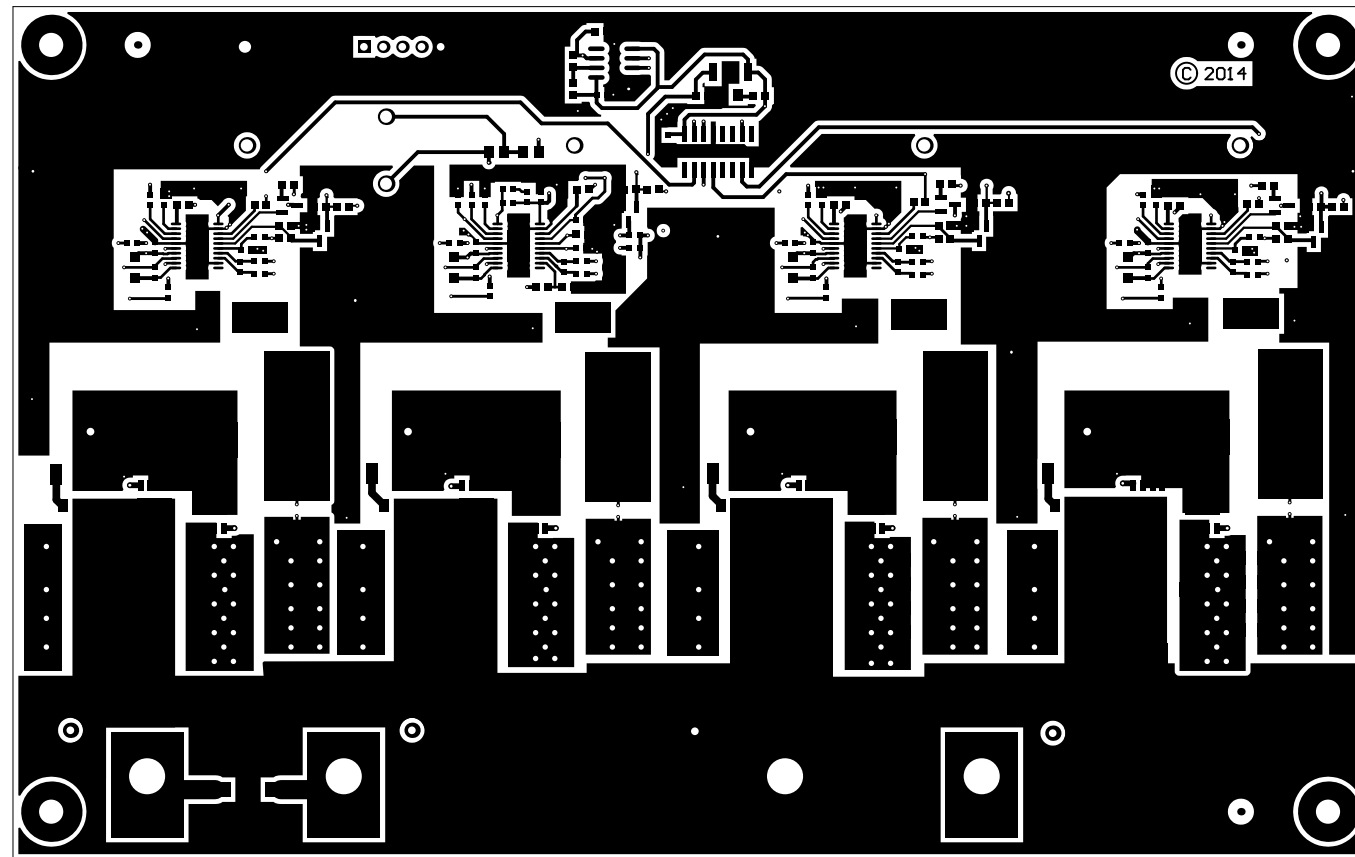


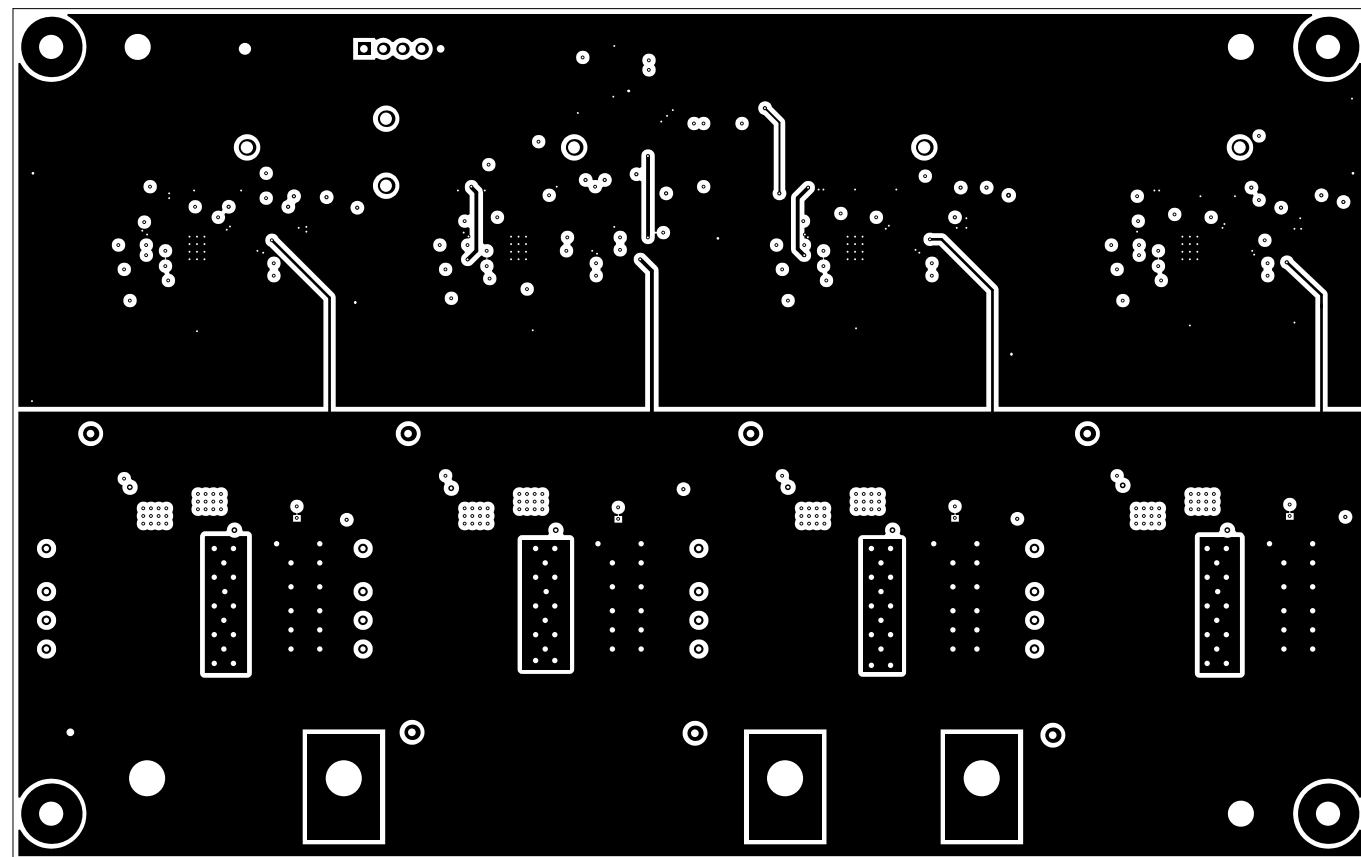
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 7/10/2014 2:56:05 PM	TEXAS INSTRUMENTS	



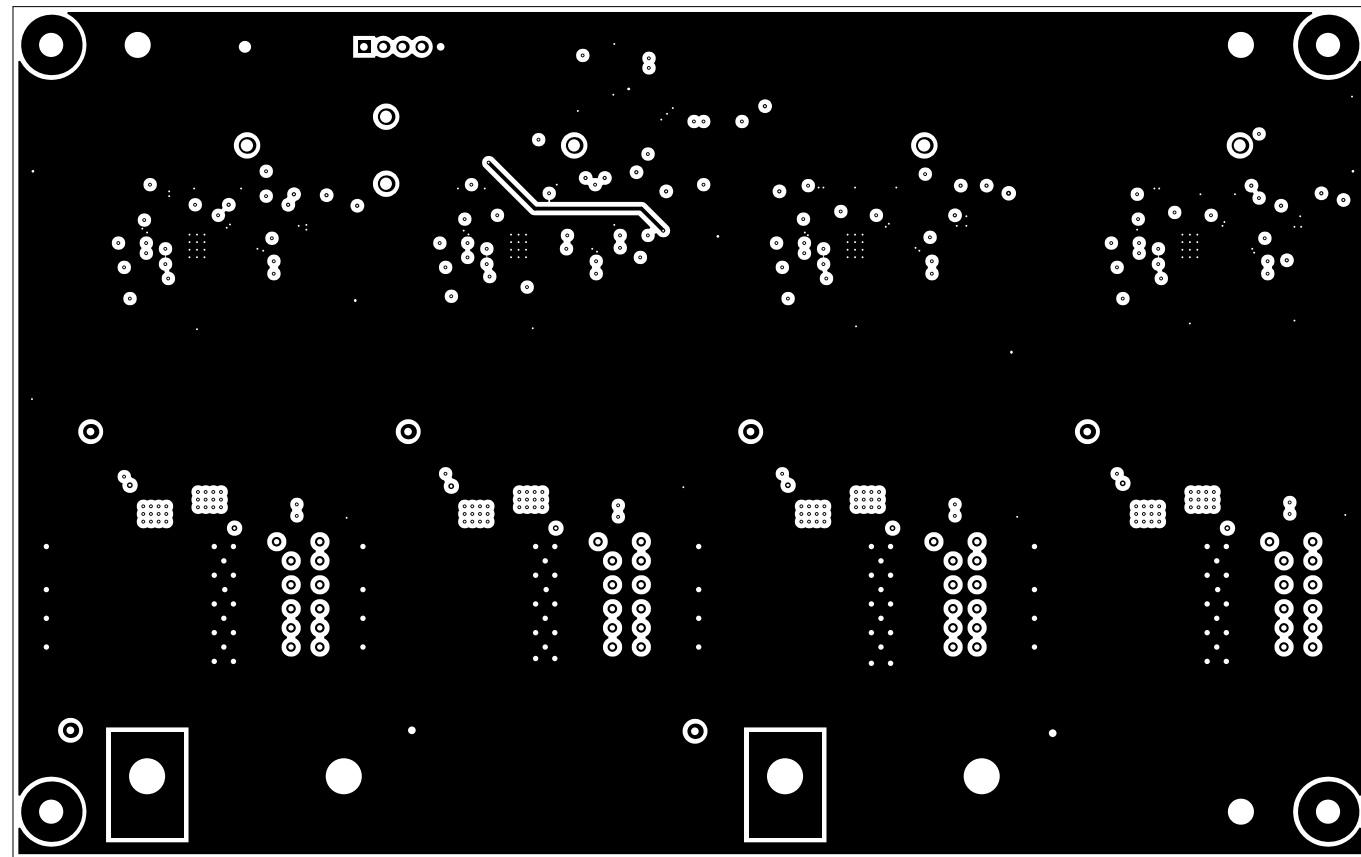
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 7/10/2014 2:56:06 PM	TEXAS INSTRUMENTS	



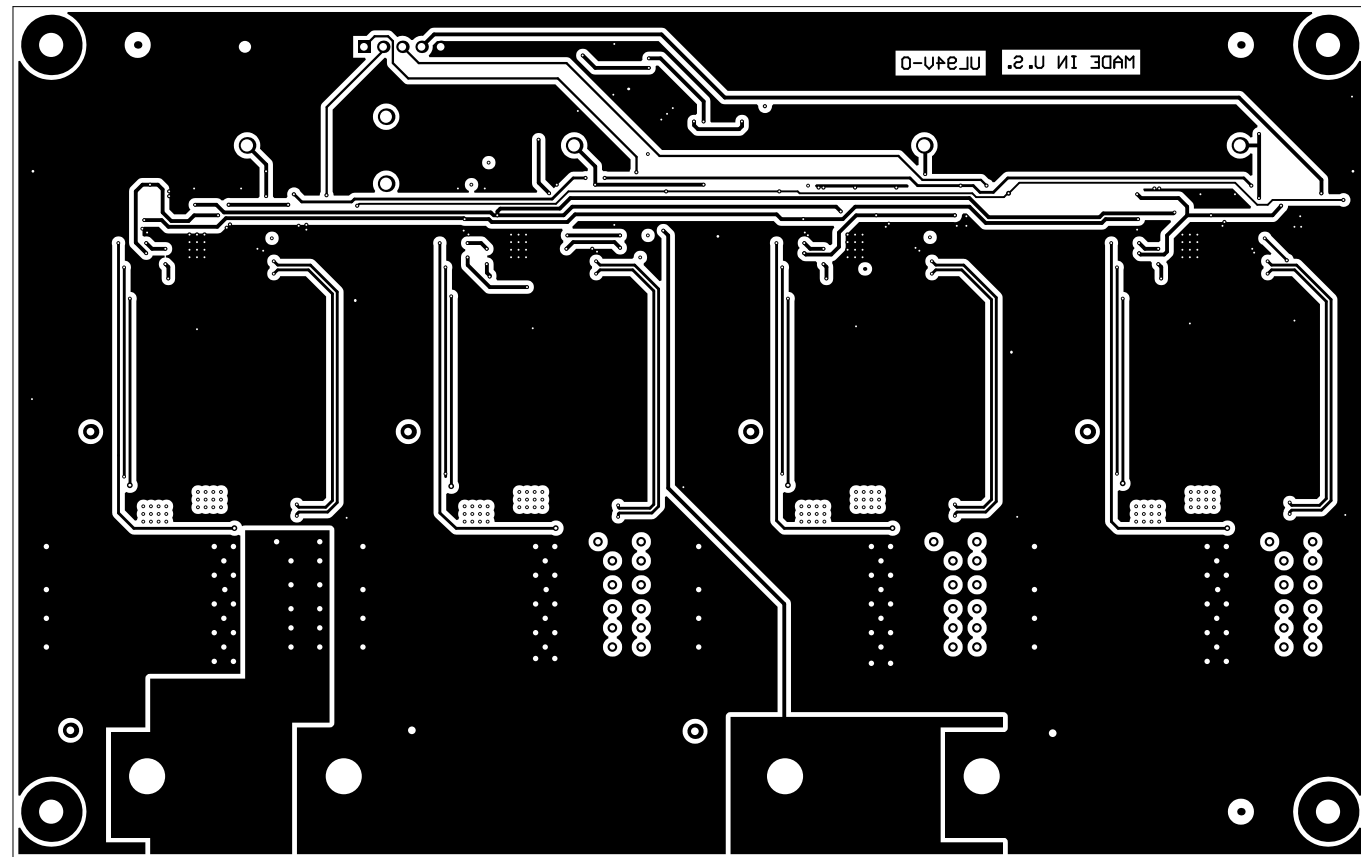
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 7/10/2014 2:56:07 PM	TEXAS INSTRUMENTS	



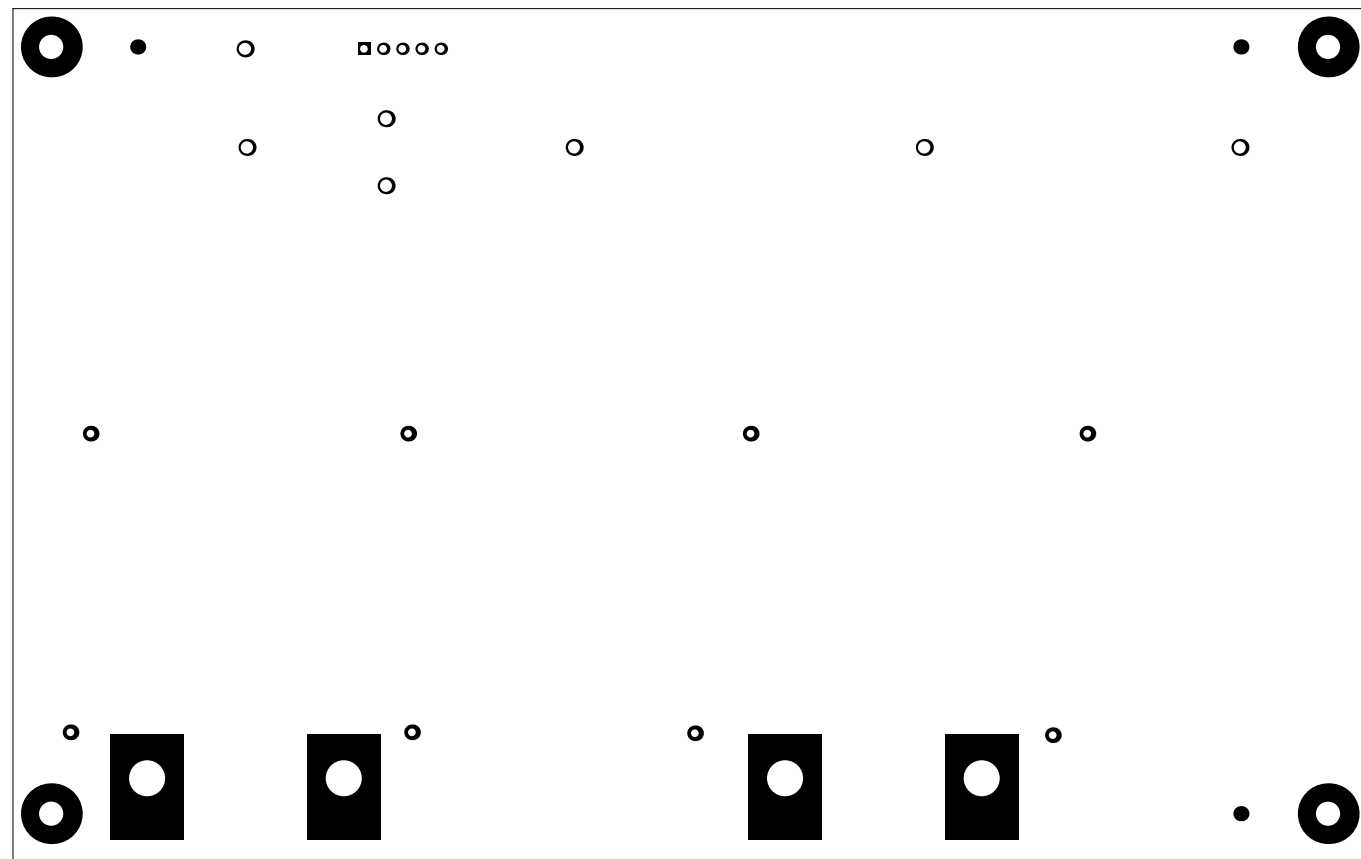
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = Mid Layer 1	GENERATED : 7/10/2014 2:56:07 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = Mid Layer 2	GENERATED : 7/10/2014 2:56:08 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 7/10/2014 2:56:08 PM	TEXAS INSTRUMENTS	



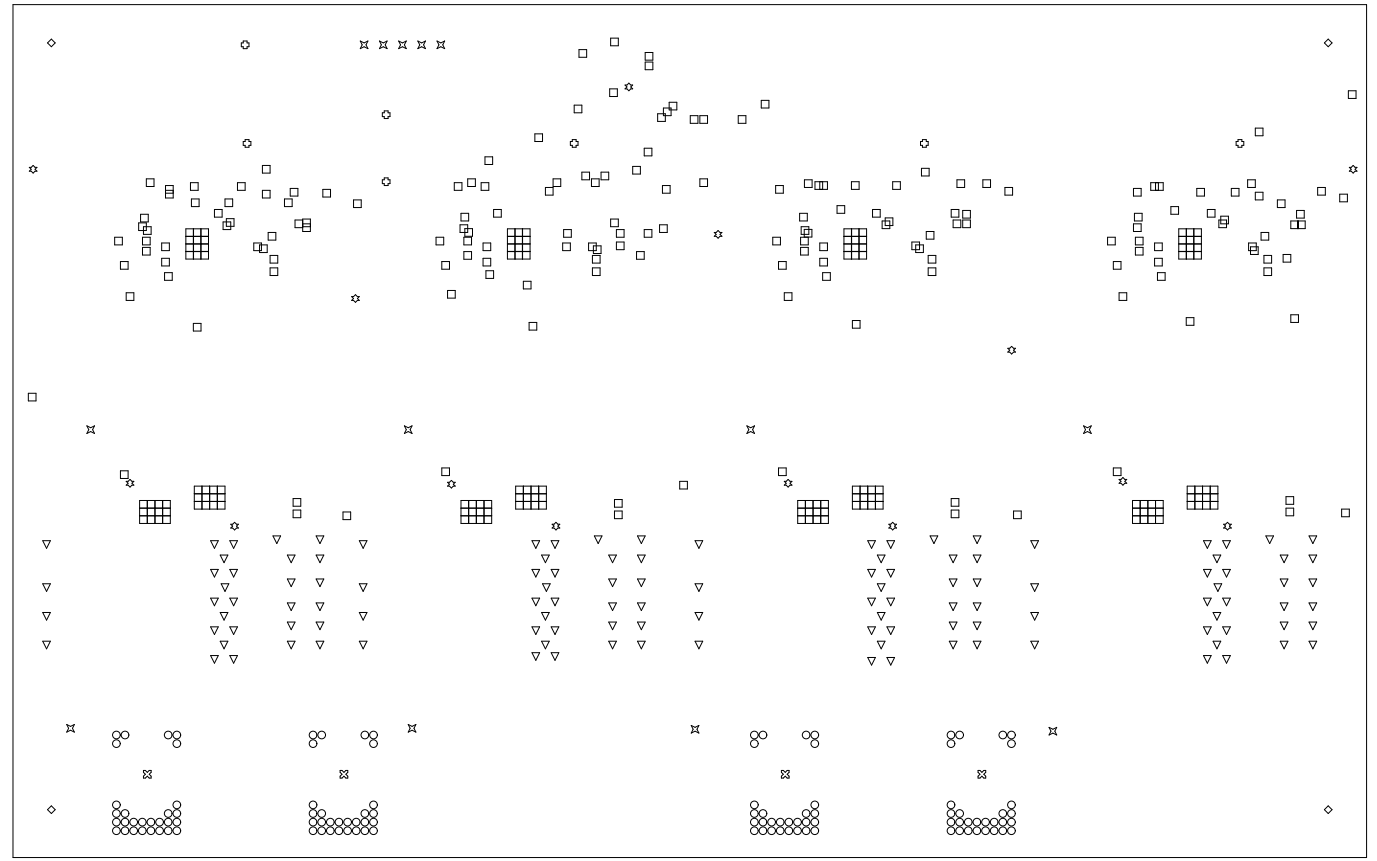
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/10/2014 2:56:09 PM	TEXAS INSTRUMENTS	



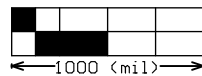
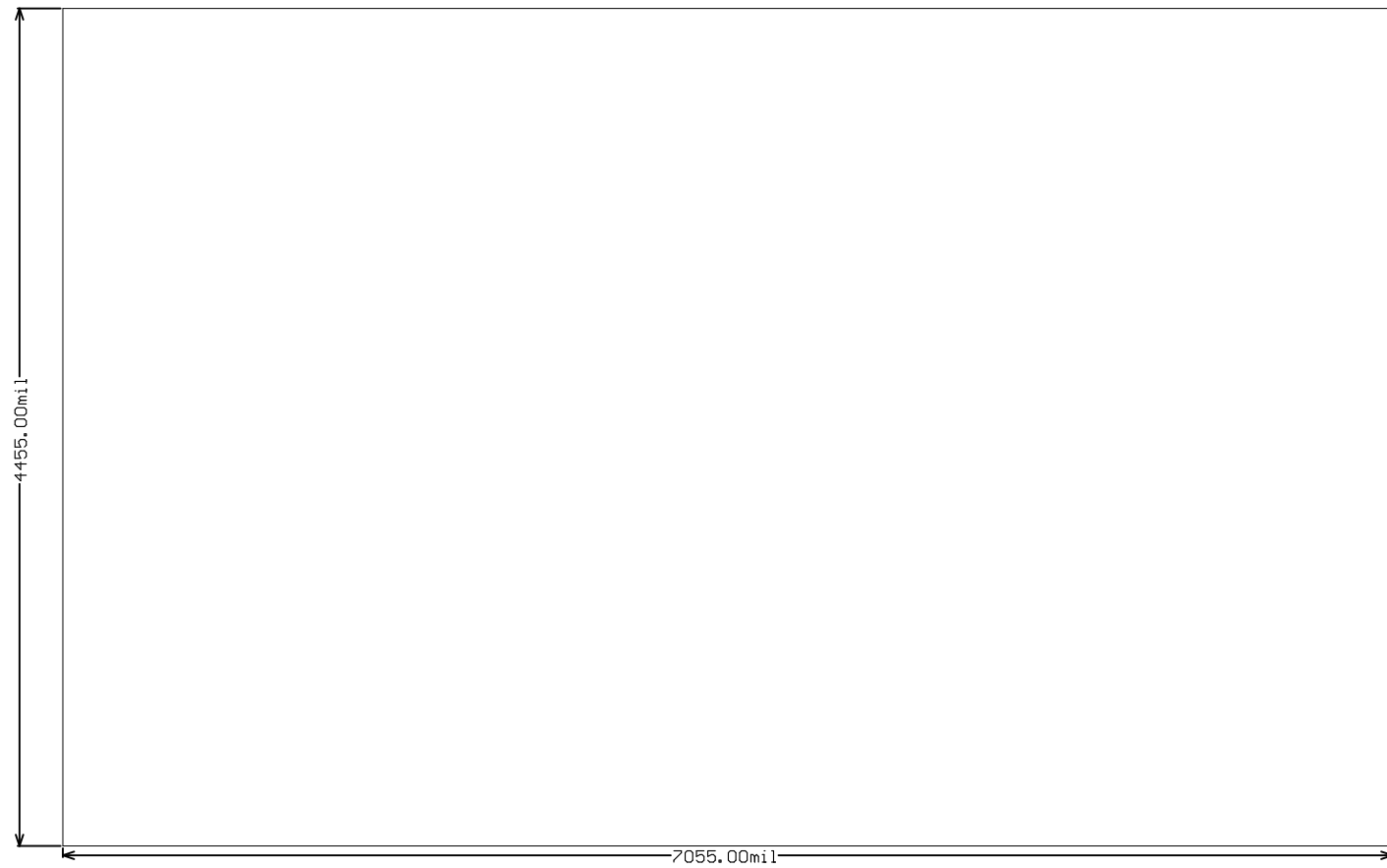
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 7/10/2014 2:56:09 PM	TEXAS INSTRUMENTS	

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	322	10mil (0.254mm)	PTH	Round
*	14	15mil (0.381mm)	PTH	Round
○	112	16mil (0.406mm)	PTH	Round
▽	120	28mil (0.711mm)	PTH	Round
×	13	40mil (1.016mm)	PTH	Round
◇	7	63mil (1.6mm)	PTH	Round
◇	4	125.984mil (3.2mm)	PTH	Round
⊗	4	188mil (4.775mm)	PTH	Round
596 Total				

Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 7/10/2014 2:56:09 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 7/10/2014 2:56:10 PM	TEXAS INSTRUMENTS	

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